

LM96163 Remote Diode Digital Temperature Sensor with Integrated Fan Control and TruTherm® BJT Transistor Beta Compensation Technology

Check for Samples: [LM96163](http://www.ti.com/product/lm96163#samples)

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- **• Smart-Tach Modes for Measuring RPM of Fans** transitions between LUT setpoints. **with Pulse-Width-Modulated Power as Shown in Typical Application Table 1. Key Specifications**
- \overline{ALERT} Output for Processor Event
- +25 to +85°C +50 to +105°C ±0.75°C **• TCRIT Output for Critical Temperature System Shutdown** $+25$ to $+85^{\circ}\text{C}$ $+40$ to $+125^{\circ}\text{C}$ $\pm 1.5^{\circ}\text{C}$
- -40 to +25°C +25 to 125°C ±3.0°C **• Offset Register Can Adjust for a Variety of Thermal Diodes**
- LM96163 Temp 25°C to 125°C ±3.0°C (max) **• 10-Bit Plus Sign and 11-Bit Unsigned Formats, with 1/8°C Resolution**
- **Extended Resolution to 1/32°C when Digital Filter Enabled**
- **• Resolves Remote Diode Temperatures up to 255.875°C**
- **• SMBus 2.0 Compatible Interface, with TIMEOUT and ARA**
- **• 10-Pin SON Package**

APPLICATIONS

- **• Processor Thermal Management**
- **• Electronic Test and Office Equipment**
- **• Industrial Controls**

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¹FEATURES DESCRIPTION

² The LM96163 has remote and local temperature **• TruTherm BJT Beta Compensation Technology** sensors with integrated fan control that includes **Supports 45nm, 65nm and 90nm Processor** TruTherm BJT transistor beta compensation
technology for remote diode sensing. The LM96163
Factory Trimmed for Intel® 45 nm Processor accurately measures: (1) its own temperature and (2) **• Factory Trimmed for Intel® 45 nm Processor** accurately measures: (1) its own temperature and (2) the temperature of a diode-connected transistor, such **• Accurately Senses Diode-Connected 2N3904** as a 2N3904, or a thermal diode commonly found on **Transistors or Thermal Diodes On-board Large** Computer Processors, Graphics Processor Units (GPU) and other ASIC's. The LM96163 has an offset **Processors or ASIC's** register to correct for errors caused by different non- **•• Accurately Senses its Own Temperature** ideality factors of other thermal diodes.

Integrated PWM Fan Speed Control Output

• Integrated PWM Fan Speed Control Output

Supports High Resolution at 22.5kHz

Frequency for 4-pin Fans

• Acoustic Fan Noise Reduction with User-

• Acoustic Fan Noise Reduction with User-

• Acoustic Fan Noise Reduction r **emote** temperature reading, the lookup table and **Programmable 12-Step Lookup Table register settings. The 12-step Lookup Table (LUT) enables the user to program a non-linear fan speed • LUT Transition Fine Resolution Smoothing** • **Function Function Find Function Function Function Find Function Find Function Find Function Find** vs. temperature transfer function often used to quiet **Function** acoustic fan noise. In addition ^a fully programmable r amping function has been added to allow smooth

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Connection Diagrams

Figure 1. 10-Pin SON (TopView) See DSC0010A Package

Pin Descriptions

Simplified Block Diagram

Typical Application

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RUMENTS

These devices have limited built-in ESD protection. The leads should be shorted together or the device placed in conductive foam during storage or handling to prevent electrostatic damage to the MOS gates.

Absolute Maximum Ratings(1)(2)(3)

(1) All voltages are measured with respect to GND, unless otherwise noted.

(2) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not guarantee performance limits. For guaranteed specifications and test conditions, see the Electrical Characteristics. The guaranteed specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.

(3) If Military/Aerospace specified devices are required, please contact the TI Sales Office/Distributors for availability and specifications. (4) When the input voltage (V_{IN}) at any pin exceeds the power supplies (V_{IN} < GND or V_{IN} > V+), the current at that pin should be limited to 5 mA. Parasitic components and/or ESD protection circuitry are shown below for the LM96163's pins. Care should be taken not to

forward bias the parasitic diode, D2, present on pins D+ and D−. Doing so by more than 50 mV may corrupt temperature measurements.

(5) Thermal resistance junction to ambient when attached to a 2 layer 4"x3" printed circuit board with copper thickness of 2oz. as described in JEDEC specification EIA/JESD51-3 is 137°C/W. Thermal resistance junction to ambient when attached to a 4 layer 4"x3" printed circuit board with copper thickness 2oz./1oz./1oz/2oz. and 4 thermal vias as described in JEDEC specification EIA/JESD51-7 is 40.3°C/W.

(6) Human body model, 100 pF discharged through a 1.5 kΩ resistor. Machine model, 200 pF discharged directly into each pin. Charged Device Model (CDM) simulates a pin slowly acquiring charge (such as from a device sliding down the feeder in an automated assembler) then rapidly being discharged.

Operating Ratings(1)(2)(3)(4)

(1) Absolute Maximum Ratings indicate limits beyond which damage to the device may occur. Operating Ratings indicate conditions for which the device is functional, but do not guarantee performance limits. For guaranteed specifications and test conditions, see the Electrical Characteristics. The guaranteed specifications apply only for the test conditions listed. Some performance characteristics may degrade when the device is not operated under the listed test conditions.

All voltages are measured with respect to GND, unless otherwise noted.

(3) Soldering process must comply with Reflow Temperature Profile specifications. Refer to www.ti.com/packaging
(4) Reflow temperature profiles are different for packages containing lead (Pb) than for those that do not.

Reflow temperature profiles are different for packages containing lead (Pb) than for those that do not.

DC Electrical Characteristics

TEMPERATURE-TO-DIGITAL CONVERTER CHARACTERISTICS

The following specifications apply for V_{DD} = 3.0 VDC to 3.6 VDC, and all analog source impedance R_S = 50 Ω unless otherwise specified in the conditions. Boldface limits apply for $T_A = T_J = T_{MIN}$ to T_{MAX} ; all other limits $T_A = +25^{\circ}$ C; unless otherwise noted. T_D is the junction temperature of the remote thermal diode. T_J is the junction temperature of the LM96163.

(1) "Typicals" are at $T_A = 25^\circ \text{C}$ and represent most likely parametric norm. They are to be used as general reference values not for critical design calculations.

Limits are guaranteed to National's AOQL (Average Outgoing Quality Level).

- (3) The accuracy of the LM96163 is guaranteed when using a typical thermal diode of an Intel processor on a 45 nm process, as selected in the Remote Diode Model Select register. See Typical Performance [Characteristics](#page-8-0) for performance with Intel processor on 65 nm or 90 nm process.
- (4) Local temperature accuracy does not include the effects of self-heating. The rise in temperature due to self-heating is the product of the internal power dissipation of the LM96163 and the thermal resistance.
- (5) Thermal resistance junction to ambient when attached to a 2 layer 4"x3" printed circuit board with copper thickness of 2oz. as described in JEDEC specification EIA/JESD51-3 is 137°C/W. Thermal resistance junction to ambient when attached to a 4 layer 4"x3" printed circuit board with copper thickness 2oz./1oz./1oz/2oz. and 4 thermal vias as described in JEDEC specification EIA/JESD51-7 is 40.3°C/W.

Operating Electrical Characteristics

(1) "Typicals" are at $T_A = 25^\circ \text{C}$ and represent most likely parametric norm. They are to be used as general reference values not for critical design calculations.

Limits are guaranteed to National's AOQL (Average Outgoing Quality Level).

(3) The supply current will not increase substantially with an SMBus transaction.

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AC Electrical Characteristics

The following specifications apply for V_{DD} = 3.0 VDC to 3.6 VDC, and all analog source impedance R_S = 50 Ω unless otherwise specified in the conditions. **Boldface limits apply for** $T_A = T_{MIN}$ **to** T_{MAX} **;** all other limits $T_A = +25^{\circ}$ C.

(1) "Typicals" are at $T_A = 25^\circ \text{C}$ and represent most likely parametric norm. They are to be used as general reference values not for critical design calculations.

(2) Limits are guaranteed to National's AOQL (Average Outgoing Quality Level).

Digital Electrical Characteristics

(1) "Typicals" are at $T_A = 25^\circ \text{C}$ and represent most likely parametric norm. They are to be used as general reference values not for critical design calculations.

(2) Limits are guaranteed to National's AOQL (Average Outgoing Quality Level).

SMBus Logical Electrical Characteristics

The following specifications apply for V_{DD} = 3.0 VDC to 3.6 VDC, and all analog source impedance R_S = 50 Ω unless otherwise specified in the conditions. **Boldface limits apply for** $T_A = T_{MIN}$ **to** T_{MAX} **; all other limits** $T_A = +25^{\circ}$ **C.**

(1) "Typicals" are at $T_A = 25^\circ \text{C}$ and represent most likely parametric norm. They are to be used as general reference values not for critical design calculations.

(2) Limits are guaranteed to National's AOQL (Average Outgoing Quality Level).

SMBus Digital Switching Characteristics

Unless otherwise noted, these specifications apply for V_{DD} = +3.0 VDC to +3.6 VDC, C_L (load capacitance) on output lines = 80 pF. **Boldface limits apply for T_A = T**_J; **T_{MIN} ≤ T_A ≤ T_{MAX};** all other limits T_A = T」 = +25°C, unless otherwise noted. The switching characteristics of the LM96163 fully meet or exceed the published specifications of the SMBus version 2.0. The following parameters are the timing relationships between SMBCLK and SMBDAT signals related to the LM96163. They adhere to but are not necessarily the same as the SMBus bus specifications.

(1) Limits are guaranteed to National's AOQL (Average Outgoing Quality Level).

(2) The output rise time is measured from $(V_{\text{IL max}} - 0.15 V)$ to $(V_{\text{IH min}} + 0.15 V)$.

(3) The output fall time is measured from $(V_{IH \text{ min}} + 0.15 V)$ to $(V_{IL \text{ max}} - 0.15 V)$.

(4) Holding the SMBDAT and/or SMBCLK lines Low for a time interval greater than t_{IMEOUT} will reset the LM96163's SMBus state machine, therefore setting SMBDAT and SMBCLK pins to a high impedance state.

Figure 2. SMBus Timing Diagram for SMBCLK and SMBDAT Signals

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Typical Performance Characteristics

Remote Temperature Reading Sensitivity to Thermal Thermal Diode Capacitor or PCB Leakage Current Effect

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FUNCTIONAL DESCRIPTION

The LM96163 Remote Diode Temperature Sensor with Integrated Fan Control incorporates a ΔV_{BF} -based temperature sensor utilizing a Local or Remote diode and a 10-bit plus sign ΔΣ ADC (Delta-Sigma Analog-to-Digital Converter). The LM96163 includes TruTherm BJT beta compensation technology that allows precision temperature sensing of remote diodes found in sub-micron processes. The pulse-width modulated (PWM) opendrain output, with a pull-up resistor, is driven by a 12-point temperature to duty cycle look-up table (LUT) and can directly drive a PWM input of a 4-pin fan in order to modulate it's speed enabling optimum system acoustic performance. The LM96163 LUT fan control algorithm also includes a smoothing function that allows the PWM duty cycle to gradually change over a programmed time interval when switching from one level to the next in the LUT. When running at a frequency of 22.5kHz the PWM output resolution is 0.39%. The LM96163 includes a TACH input that can measure the speed of a fan using the pulses from a 3 or 4 pin fan's tachometer output. The LM96163 includes a smart-tach measurement mode to accommodate the corrupted tachometer pulses when using switching transistor power drive to modulate the fan speed. The LM96163 has an ALERT open-drain output that will be pulled low when the measured temperature exceeds certain programmed limits when enabled. Details are contained in the sections below.

The LM96163's two-wire interface is compatible with the SMBus Specification 2.0 . For more information the reader is directed to www.smbus.org.

In the LM96163 digital comparators are used to compare the measured Local Temperature (LT) to the Local High Setpoint user-programmable temperature limit register. The measured Remote Temperature (RT) is digitally compared to the Remote High Setpoint (RHS), the Remote Low Setpoint (RLS), and the Remote T_CRIT Setpoint (RCS) user-programmable temperature limits. An ALERT output will occur when the measured temperature is: (1) higher than either the High Setpoint or the T_CRIT Setpoint, or (2) lower than the Low Setpoint. The ALERT Mask register allows the user to prevent the generation of these ALERT outputs. A TCRIT output will occur when the measured temperature is higher than the T_CRIT Setpoint.

The TCRIT function and the look-up table temperature hysteresis can be set separately. The hysteresis value associated with the TCRIT output is set in the Remote T_CRIT Hysteresis Register. The value associated with the look-up table function is set in the Lookup Table Hysteresis Register.

The LM96163 may be placed in a low power Standby mode by setting the Standby bit found in the Configuration Register. In the Standby mode continuous conversions are stopped. In Standby mode the user may choose to allow the PWM output signal to continue, or not, by programming the PWM Disable in Standby bit in the Configuration Register.

The Local Temperature reading and setpoint data registers are 8-bits wide. The format of the 11-bit remote temperature data is a 16-bit left justified word. Two 8-bit registers, high and low bytes, are provided for each setpoint as well as the temperature reading. A digital filter may be invoked for remote temperature readings that increases the resolution from 11-bits to 13-bits. The temperature readings are also available in an unsigned format allowing resolution above 127°C. Two Remote Temperature Offset (RTO) Registers: High Byte and Low Byte (RTOHB and RTOLB) may be used to correct the temperature readings by adding or subtracting a fixed value based on a different non-ideality factor and series resistance of the thermal diode if different from the thermal diode found in the Intel processors on 45 nm process. See section DIODE [NON-IDEALITY](#page-37-0).

ALERT and TCRIT OUTPUTS

In this section we will address the ALERT and TCRIT active-low open-drain output functions. When the ALERT Mask bit in the Configuration register is written as zero the ALERT interrupts are enabled.

The LM96163's ALERT pin is versatile and can produce three different methods of use to best serve the system designer: (1) as a temperature comparator (2) as a temperature-based interrupt flag, and (3) as part of an SMBus ALERT System. The three methods of use are further described below. The ALERT and interrupt methods are different only in how the user interacts with the LM96163.

The remote temperature (RT) reading is associated with a T_CRIT Setpoint Register, and both local and remote temperature (LT and RT) readings are associated with a HIGH setpoint register (LHS and RHS). The RT is also associated with a LOW setpoint register (RLS). At the end of every temperature reading a digital comparison determines whether that reading is above its HIGH or T_CRIT setpoint or below its LOW setpoint. If so, the corresponding bit in the ALERT Status Register is set. If the ALERT mask bit is low, any bit set in the ALERT Status Register, with the exception of Busy or RDFA, will cause the ALERT output to be pulled low. Any temperature conversion that is out of the limits defined in the temperature setpoint registers will trigger an ALERT. Additionally, the ALERT Mask Bit must be cleared to trigger an ALERT in all modes.

The format of the Remote High limit and T_CRIT limit comparison is programmable. The USF bit found in the Enhanced Configuration register controls whether comparisons use a signed or unsigned format. The temperature format used for Remote High and T_CRIT limit comparisons is +255.875 °C to -256 °C.

The three different ALERT modes and TCRIT function will be discussed in the following sections.

ALERT Output as a Temperature Comparator

When the LM96163 is used in a system in which does not require temperature-based interrupts, the ALERT output could be used as a temperature comparator. In this mode, once the condition that triggered the ALERT to go low is no longer present, the ALERT is negated ([Figure](#page-10-0) 8). For example, if the ALERT output was activated by the comparison of LT > LHS, when this condition is no longer true, the ALERT will return HIGH. This mode allows operation without software intervention, once all registers are configured during set-up. In order for the ALERT to be used as a temperature comparator, the Comparator Mode bit in the Remote Diode Temperature Filter and Comparator Mode Register must be asserted. This is not the power-on default state.

Figure 8. ALERT Output as Temperature Comparator Response Diagram

ALERT Output as an Interrupt

The LM96163's ALERT output can be implemented as a simple interrupt signal when it is used to trigger an interrupt service routine. In such systems it is desirable for the interrupt flag to repeatedly trigger during or before the interrupt service routine has been completed. Under this method of operation, during the read of the ALERT Status Register the LM96163 will set the ALERT Mask bit in the Configuration Register if any bit in the ALERT Status Register is set, with the exception of Busy and RDFA. This prevents further ALERT triggering until the master has reset the ALERT Mask bit, at the end of the interrupt service routine. The ALERT Status Register bits are cleared only upon a read command from the master (see [Figure](#page-11-0) 9) and will be re-asserted at the end of the next conversion if the triggering condition(s) persist(s). In order for the ALERT to be used as a dedicated interrupt signal, the Comparator Mode bit in the Remote Diode Temperature Filter and Comparator Mode Register must be set low. This is the power-on default state. The following sequence describes the response of a system that uses the ALERT output pin as an interrupt flag:

- 1. Master senses ALERT low.
- 2. Master reads the LM96163 ALERT Status Register to determine what caused the ALERT.
- 3. LM96163 clears ALERT Status Register, resets the ALERT HIGH and sets the ALERT Mask bit in the Configuration Register.
- 4. Master attends to conditions that caused the ALERT to be triggered. The fan is started, setpoint limits are adjusted, etc.
- 5. Master resets the ALERT Mask bit in the Configuration Register.

Figure 9. ALERT Output as an Interrupt Temperature Response Diagram

ALERT Output as an SMBus ALERT

An SMBus alert line is created when the ALERT output is connected to: (1) one or more ALERT outputs of other SMBus compatible devices, and (2) to a master. Under this implementation, the LM96163's ALERT should be operated using the ARA (Alert Response Address) protocol. The SMBus 2.0 ARA protocol, defined in the SMBus specification 2.0, is a procedure designed to assist the master in determining which part generated an interrupt and to service that interrupt.

The SMBus alert line is connected to the open-drain ports of all devices on the bus, thereby AND'ing them together. The ARA method allows the SMBus master, with one command, to identify which part is pulling the SMBus alert line LOW. It also prevents the part from pulling the line LOW again for the same triggering condition. When an ARA command is received by all devices on the bus, the devices pulling the SMBus alert line LOW: (1) send their address to the master and (2) release the SMBus alert line after acknowledgement of their address.

The SMBus Specifications 1.1 and 2.0 state that in response to and ARA (Alert Response Address) "after acknowledging the slave address the device must disengage its ALERT pulldown". Furthermore, "if the host still sees ALERT low when the message transfer is complete, it knows to read the ARA again." This SMBus "disengaging ALERT requirement prevents locking up the SMBus alert line. Competitive parts may address the "disengaging of ALERT" differently than the LM96163 or not at all. SMBus systems that implement the ARA protocol as suggested for the LM96163 will be fully compatible with all competitive parts.

The LM96163 fulfills "disengaging of ALERT" by setting the ALERT Mask Bit in the Configuration Register after sending out its address in response to an ARA and releasing the ALERT output pin. Once the ALERT Mask bit is activated, the ALERT output pin will be disabled until enabled by software. In order to enable the ALERT the master must read the ALERT Status Register, during the interrupt service routine and then reset the ALERT Mask bit in the Configuration Register to 0 at the end of the interrupt service routine.

The following sequence describes the ARA response protocol.

- 1. Master senses SMBus alert line low
- 2. Master sends a START followed by the Alert Response Address (ARA) with a Read Command.
- 3. Alerting Device(s) send ACK.
- 4. Alerting Device(s) send their address. While transmitting their address, alerting devices sense whether their address has been transmitted correctly. (The LM96163 will reset its ALERT output and set the ALERT Mask bit once its complete address has been transmitted successfully.)
- 5. Master/slave NoACK
- 6. Master sends STOP
- 7. Master attends to conditions that caused the ALERT to be triggered. The ALERT Status Register is read and fan started, setpoints adjusted, etc.
- 8. Master resets the ALERT Mask bit in the Configuration Register.

The ARA, 000 1100, is a general call address. No device should ever be assigned to this address.

The ALERT Configuration bit in the Remote Diode Temperature Filter and Comparator Mode Register must be set low in order for the LM96163 to respond to the ARA command.

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The ALERT output can be disabled by setting the ALERT Mask bit in the Configuration Register. The power-on default is to have the ALERT Mask bit and the ALERT Configuration bit low.

Figure 10. ALERT Output as an SMBus ALERT Temperature Response Diagram

TCRIT Function

The TCRIT output will be activated whenever the RCRIT bit in the ALERT Status register is set. This occurs whenever the remote temperature exceeds the value set by the Remote T_CRIT Setpoint register. There is a hysteresis associated with the T_CRIT Setpoint that is set by the value in the Remote T_CRIT Hysteresis register. The RCRIT bit will be reset when the remote temperature equals or is less than the value defined by Remote T_CRIT Setpoint minus T_CRIT Hysteresis. The resolution of the comparison is 1 °C. For example if T_CRIT = 110 °C and THYST = 5 °C the TCRIT output will activate when the temperature reading is 111 °C and deactivate when the temperature reading is 105 °C.

When the LM96163 powers up the T_CRIT limit is locked to the default value. It may be changed after the T_CRIT Limit Override bit (TCRITOV) bit, found in the Configuration Register, is set.

The format of the Remote T_CRIT setpoint register is controlled by the USF bit found in the Enhanced configuration register. The temperature reading format used for the T_CRIT comparisons is +255 °C to -256°C.

SMBus INTERFACE

Since the LM96163 operates as a slave on the SMBus the SMBCLK line is an input and the SMBDAT line is bidirectional. The LM96163 never drives the SMBCLK line and it does not support clock stretching. According to SMBus specifications, the LM96163 has a 7-bit slave address. All bits, A6 through A0, are internally programmed and cannot be changed by software or hardware.

The complete slave address is:

POWER-ON RESET (POR) DEFAULT STATES

For information on the POR default states see Register Map in [Functional](#page-19-0) Order.

TEMPERATURE DATA FORMAT

Temperature data can only be read from the Local and Remote Temperature value registers. The data format for all temperature values is left justified 16-bit word available in two 8-bit registers. Unused bits will always report "0". All temperature data is clamped and will not roll over when a temperature exceeds full-scale value.

Remote temperature and remote high setpoint temperature data can be represented by an 11-bit, two's complement word or unsigned binary word with an LSb (Least Significant Bit) equal to 0.125°C.

Texas **STRUMENTS**

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Table 2. 11-bit, 2's complement (10-bit plus sign)

Table 3. 11-bit, unsigned binary

When the digital filter is enabled on the remote channel, temperature data is represented by a 13-bit unsigned binary or 12-bit plus sign (two's complement) word with an LSb equal to 0.03125°C.

Table 4. 13-bit, 2's complement (12-bit plus sign)

Table 5. 13-bit, unsigned binary

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Table 5. 13-bit, unsigned binary (continued)

Local Temperature and Remote T_CRIT setpoint data is represented by an 8-bit, two's complement, word with an LSb equal to 1°C.

Remote T_CRIT setpoint data can also be represented by an 8-bit, unsigned, word with an LSb equal to 1°C.

Table 7. 8-bit, unsigned binary

OPEN-DRAIN OUTPUTS

The SMBDAT, ALERT, TCRIT and PWM outputs are open-drain outputs and do not have internal pull-ups. A "High" level will not be observed on these pins until pull-up current is provided by an internal source, typically through a pull-up resistor. Choice of resistor value depends on several factors but, in general, the value should be as high as possible consistent with reliable operation. This will lower the power dissipation of the LM96163 and avoid temperature errors caused by self-heating of the device. The maximum value of the pull-up resistor to provide the 2.1 V high level is 88.7 kΩ.

DIODE FAULT DETECTION

The LM96163 is equipped with operational circuitry designed to detect remote diode fault conditions:

- D+ shorted to V_{DD}
- D+ open or floating
- D+ shorted to GND.

In the event that the D+ pin is grounded the Remote Temperature reading is forced to -128.000 °C if signed format is read and 0 °C if unsigned format is read. When the D+ pin is detected as shorted to V_{DD} or floating, the Remote Temperature reading is forced to +127.000 °C if signed format is read and +255.000 °C is unsigned format is read. In addition, the ALERT Status register bit RDFA is set. Setting of the RDFA bit will not cause ALERT or TCRIT to activate. Under fault conditions remote diode setpoint comparisons will use these forced temperature values therefore other bits in the ALERT Status Register may be set thus activating the ALERT or TCRIT outputs unless these bits are masked. The function of the ALERT and TCRIT is fully described in Section ALERT and TCRIT [OUTPUTS.](#page-9-0)

COMMUNICATING WITH THE LM96163

Each data register in the LM96163 falls into one of four types of user accessibility:

- 1. Read Only
- 2. Write Only
- 3. Read/Write same address
- 4. Read/Write different address

A Write to the LM96163 is comprised of an address byte and a command byte. A write to any register requires one data byte.

Reading the LM96163 Registers can take place after the requisite register setup sequence takes place. See Required Initial Fan Control Register [Sequence.](#page-20-0)

The data byte has the Most Significant Bit (MSB) first. At the end of a read, the LM96163 can accept either Acknowledge or No-Acknowledge from the Master. Note that the No-Acknowledge is typically used as a signal for the slave indicating that the Master has read its last byte.

DIGITAL FILTER

TEMPERATURE (°C)

In order to suppress erroneous remote temperature readings due to noise as well as increase the resolution of the temperature, the LM96163 incorporates a digital filter for remote temperature readings. The filter is accessed in the Remote Diode Temperature Filter and Comparator Mode Register. The filter can be set according to the following table.

[Figure](#page-15-0) 11 describes the filter output in response to a step input and an impulse input.

The filter curves were purposely offset for clarity.

Figure 12. Digital Filter Response in a typical Intel processor on a 65 nm or 90 nm process

[Figure](#page-16-0) 12 shows the filter in use in a typical Intel processor on a 65/90 nm process system. Note that the two curves have been purposely offset for clarity. Inserting the filter does not induce an offset as shown.

FAULT QUEUE

The LM96163 incorporates a Fault Queue to suppress erroneous ALERT triggering . The Fault Queue prevents false triggering by requiring three consecutive out-of-limit HIGH or LOW temperature readings. See [Figure](#page-16-1) 13. The Fault Queue defaults to OFF upon power-up and may be activated by setting the RDTS Fault Queue bit in the Configuration Register to a 1.

Figure 13. Fault Queue Temperature Response Diagram

ONE-SHOT REGISTER

The One-Shot Register is used to initiate a single conversion and comparison cycle when the device is in standby mode, after which the data returns to standby. This is not a data register. A write operation causes the one-shot conversion. The data written to this address is irrelevant and is not stored. A zero will always be read from this register.

SERIAL INTERFACE RESET

In the event that the SMBus Master is reset while the LM96163 is transmitting on the SMBDAT line, the LM96163 must be returned to a known state in the communication protocol. This may be done in one of two ways:

1. When SMBDAT is Low, the LM96163 SMBus state machine resets to the SMBus idle state if either SMBDAT or SMBCLK are held Low for more than 35 ms ($t_{TIMEOUT}$). Devices are to timeout when either the SMBCLK or SMBDAT lines are held Low for 25 ms – 35 ms. Therefore, to insure a timeout of devices on the bus, either the SMBCLK or the SMBDAT line must be held Low for at least 35 ms.

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2. With both SMBDAT and SMBCLK High, the master can initiate an SMBus start condition with a High to Low transition on the SMBDAT line. The LM96163 will respond properly to an SMBus start condition at any point during the communication. After the start the LM96163 will expect an SMBus Address address byte.

LM96163 REGISTERS

The following pages include: LM96163 REGISTER MAP IN [HEXADECIMAL](#page-17-0) ORDER, which shows a summary of all registers and their bit assignments, LM96163 REGISTER MAP IN [FUNCTIONAL](#page-19-0) ORDER, and [LM96163](#page-21-0) DETAILED REGISTER [DESCRIPTIONS](#page-21-0) IN FUNCTIONAL ORDER, a detailed explanation of each register. Do not address the unused or manufacturer's test registers.

LM96163 REGISTER MAP IN HEXADECIMAL ORDER

The following is a Register Map grouped in hexadecimal address order. Some address locations have been left blank to maintain compatibility with LM86, LM63 and LM64. Addresses in parenthesis are mirrors of "Same As" address for backwards compatibility with some older software. Reading or writing either address will access the same 8-bit register.

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LM96163 REGISTER MAP IN FUNCTIONAL ORDER

The following is a Register Map grouped in Functional Order. Some address locations have been left blank to maintain compatibility with LM86. Addresses in parenthesis are mirrors of named address. Reading or writing either address will access the same 8-bit register. The Fan Control and Configuration Registers are listed first, as there is a required order to setup these registers first and then setup the others. The detailed explanations of each register will follow the order shown below. POR = Power-On-Reset.

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LM96163 REQUIRED INITIAL FAN CONTROL REGISTER SEQUENCE

Important! The BIOS or firmware must follow the sequence below to configure the following Fan Registers for the LM96163 before using any of the Fan or Tachometer or PWM registers:

(1) All other registers can be written at any time after the above sequence.

LM96163 DETAILED REGISTER DESCRIPTIONS IN FUNCTIONAL ORDER

The following is a Register Map grouped in functional and sequence order. New register addresses have been added to maintain compatibility with the LM63 and LM64 register sets. Addresses in parenthesis are mirrors of named address for backwards compatibility with some older software. Reading or writing either address will access the same 8-bit register.

Fan Control Registers

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Configuration Register

Tachometer Count and Limit Registers

Local Temperature and Local High Setpoint Registers

Remote Diode Temperature, Offset and Setpoint Registers

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ALERT Status and Mask Registers

Texas
Instruments

Conversion Rate and One-Shot Registers

ID Registers

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APPLICATION NOTES

FAN CONTROL DUTY CYCLE VS. REGISTER SETTINGS AND FREQUENCY

NOTE

The following table is true only when the 22.5 kHz PWM frequency high resolution duty cycle is not selected.

NOTE

The following table is true only when the 22.5 kHz PWM frequency with high resolution duty cycle is selected by setting bit 4 (PHR) of the Enhanced Configuration register (0x45), clearing bit 3 (PWCKSL) of the PWM and RPM Configuration register (0x4A) and setting PWM Frequency (0x4D) register to 0x08.

Computing Duty Cycles for a Given Frequency

Select a PWM Frequency from the first column corresponding to the desired actual frequency in columns 6 or 7. Note the PWM Value for 100% Duty Cycle.

Find the Duty Cycle by taking the PWM Value of Register 4C and computing:

$$
DutyCycle_{0}(%) = \frac{PWM_{value}}{PWM_{value_{0}} for_{0.100\%}} \times 100\%
$$

(1)

Example: For a PWM Frequency of 24, a PWM Value at 100% = 48 and PWM Value actual = 28, then the Duty Cycle is (28/48) × 100% = **58.3%**.

LUT FAN CONTROL

The LM96163 fan control uses a temperature to duty cycle look-up table (LUT) that has 12 indexes. High resolution duty cycle (0.392%) is available when the PWM frequency is set to 22.5 kHz. In addition ramp rate control is available to acoustically smooth the duty cycle transition between LUT steps.

Shown in [Figure](#page-36-0) 14 (a) is an example of the 12-point LUT temperature to PWM transfer function that can be realized without smoothing enabled. The table is comprised of twelve Duty-Cycle and Temperature set-point pairs. Notice that the transitions between one index of the LUT to the next happen instantaneously. If the PWM levels are set far enough apart this can be acoustically very disturbing. The typical acoustical threshold of change in duty cycle is 2%. [Figure](#page-36-0) 14 (b) has an overlaid curve (solid line) showing what occurs at the transitions when smoothing is enabled. The dashed lines shown in [Figure](#page-36-0) 14 (b) are there to point out that multiple slopes can be realized easily. At the transitions the duty cycle increments in LSb (0.39% for the case shown) steps. In the example shown in [Figure](#page-36-0) 14 (b) the first pair is set for a duty-cycle of 31.25% and a temperature of 0°C. For temperatures less than 0°C the duty cycle is set to 0. When the temperature is greater than 0 °C but is less than 91 °C the duty cycle will remain at 31.25%. The next pair is set at 37.5% and 91°C. Once the temperature exceeds 91°C the duty cycle on the PWM output will gradually transition from 31.25% to 37.5% in 0.39% steps at the programmed time interval. The LUT comparison temperature resolution is programmable to either 1 °C or 0.5 °C. For the curves of [Figure](#page-36-0) 14 the comparison resolution is set to 0.5 °C that is why the actual duty cycle transitions happen 0.5 °C higher than the actual LUT entry. The duty cycle transition time interval is programmable and is shown in the table titled [Table](#page-36-1) 8. Care should be taken so that the LUT PWM and Temperature values are setup in ascending weight.

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Also included is programmable hysteresis that is not described by the curves of [Figure](#page-36-0) 14. The hysteresis takes effect as temperature is decreasing and moves all the temperature set-points down by the programmed amount. For the example shown here if the hysteresis is set to 1°C and if the temperature is decreasing from 96.5°C the duty cycle will remain at 68.75% and will not transition to 62.5% until the temperature drops below 95.5°C.

If at any time the TCRIT output were to activate the PWM duty cycle will be instantaneously forced to 100% thus forcing the fans to full on.

The [Table](#page-36-1) 8 table describes the programmable time interval preventing abrupt changes in the PWM output duty cycle and thus preventing abrupt acoustical noise changes as well. The threshold of acoustically detecting fan noise transition is at about a 2% duty cycle change. The table describes the time intervals that can be programmed and the total amount of time it will take for the PWM output to change from 0% to 100% for each time interval. For example if the time interval for each step is set to 0.091 seconds the time it will take to make a 0 to 100% duty cycle change will be 21.6 seconds when the duty cycle resolution is set to 0.39% or 1.46 seconds when the resolution is 6.25%. One setting will apply to all LUT transitions.

COMPUTING RPM OF THE FAN FROM THE TACH COUNT

The Tach Count Registers 46_{HEX} and 47_{HEX} count the number of periods of the 90 kHz tachometer clock in the LM96163 for the tachometer input from the fan assuming a 2 pulse per revolution fan tachometer, such as the fans supplied with the Intel boxed processors. The RPM of the fan can be computed from the Tach Count Registers 46_{HEX} and 47_{HEX} . This can best be shown through an example.

Example:

Given: the fan used has a tachometer output with 2 per revolution.

Let:

Register 46 (LSB) is BF_{HEX} = Decimal (11 x 16) + 15 = 191 and

STRUMENTS

Register 47 (MSB) is 7_{HEX} = Decimal (7 x 256) = 1792. The total Tach Count, in decimal, is 191 + 1792 = **1983**. The RPM is computed using the formula

$$
Fan = RPM = \frac{f \times 5,400,000}{Total = Tach = Count (Decimal)}
$$

where

 $f = 1$ for 2 pulses/rev fan tachometer output;

 $f = 2$ for 1 pulse/rev fan tachometer output, and

 $f = 2 / 3$ for 3 pulses/rev fan tachometer output

For our example

$$
Fan = RPM = \frac{1 \times 5,400,000}{1983} = 2723 = RPM
$$

DIODE NON-IDEALITY

The LM96163 can be applied easily in the same way as other integrated-circuit temperature sensors, and its remote diode sensing capability allows it to be used in new ways as well. It can be soldered to a printed circuit board, and because the path of best thermal conductivity is between the die and the pins, its temperature will effectively be that of the printed circuit board lands and traces soldered to the LM96163's pins. This presumes that the ambient air temperature is almost the same as the surface temperature of the printed circuit board; if the air temperature is much higher or lower than the surface temperature, the actual temperature of the LM96163 die will be at an intermediate temperature between the surface and air temperatures. Again, the primary thermal conduction path is through the leads, so the circuit board temperature will contribute to the die temperature much more strongly than will the air temperature.

,

The LM96163 incorporates remote diode temperature sensing technology allowing the measurement of remote temperatures. This diode can be located on the die of a target IC, allowing measurement of the IC's temperature, independent of the LM96163's die temperature. A discrete diode can also be used to sense the temperature of external objects or ambient air. Remember that a discrete diode's temperature will be affected, and often dominated, by the temperature of its leads. Most silicon diodes do not lend themselves well to this application. It is recommended that an MMBT3904 transistor base emitter junction be used with the collector tied to the base.

The LM96163's TruTherm BJT beta compensation technology allows accurate sensing of integrated thermal diodes, such as those found on most processors. With TruTherm technology turned off, the LM96163 can measure a diode-connected transistor such as the MMBT3904 or the thermal diode found in an AMD processor.

The LM96163 has been optimized to measure the remote thermal diode integrated in a typical Intel processor on 45nm, 65 nm or 90 nm process or an MMBT3904 transistor. Using the Remote Diode TruTherm Enable register the remote input can be optimized for a typical Intel processor on 45nm, 65 nm or 90 nm process or an MMBT3904.

Diode Non-Ideality Factor Effect on Accuracy

When a transistor is connected as a diode, the following relationship holds for variables V_{BE} , T and I_{F} :

$$
I_F = I_S \times \left[e^{\left(\frac{V_{BE}}{\eta \times V_t}\right)} - 1 \right]
$$

:

$$
V_t = \frac{kT}{r}
$$

where:

$$
V_t = \frac{kT}{q}
$$

(5)

(4)

(2)

(3)

(6)

(8)

(9)

- q = 1.6×10⁻¹⁹ Coulombs (the electron charge),
- $T =$ Absolute Temperature in Kelvin
- $k = 1.38 \times 10^{-23}$ joules/K (Boltzmann's constant),
- η is the non-ideality factor of the process the diode is manufactured on,
- I_S = Saturation Current and is process dependent,
- I_f = Forward Current through the base-emitter junction
- V_{BE} = Base-Emitter Voltage drop

In the active region, the -1 term is negligible and may be eliminated, yielding the following equation

$$
I_F = I_S \times \left[e^{\left(\frac{V_{BE}}{\eta \times V_t}\right)} \right]
$$

In [Equation](#page-38-0) 6, η and I_s are dependant upon the process that was used in the fabrication of the particular diode. By forcing two currents with a very controlled ratio(I_{F2} / I_{F1}) and measuring the resulting voltage difference, it is possible to eliminate the I_S term. Solving for the forward voltage difference yields the relationship:

$$
\Delta V_{BE} = \eta \times \left(\frac{kT}{q}\right) \times \ln\left(\frac{I_{F2}}{I_{F1}}\right) \tag{7}
$$

Solving [Equation](#page-38-1) 7 for temperature yields:

$$
T = \frac{q \times \Delta V_{BE}}{q \times \Delta V_{BE}}
$$

$$
T = \frac{q \times \Delta V_{BE}}{q \times k \times \ln\left(\frac{I_{F2}}{I_{F1}}\right)}
$$

[Equation](#page-38-2) 8 holds true when a diode connected transistor such as the MMBT3904 is used. When this "diode" equation is applied to an integrated diode such as a processor transistor with its collector tied to GND as shown in [Figure](#page-38-3) 15 it will yield a wide non-ideality spread. This wide non-ideality spread is not due to true process variation but due to the fact that [Equation](#page-38-2) 8 is an approximation.

TruTherm BJT beta compensation technology uses the transistor equation, [Equation](#page-38-4) 9, which is a more accurate representation of the topology of the thermal diode found in an FPGA or processor.

$$
T = \frac{q \times \Delta V_{BE}}{\eta \times k \times \ln\left(\frac{I_{C2}}{I_{C1}}\right)}
$$

TruTherm should only be enabled when measuring the temperature of a transistor integrated as shown in the processor of [Figure](#page-38-3) 15, because [Equation](#page-38-4) 9 only applies to this topology.

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Calculating Total System Accuracy

The voltage seen by the LM96163 also includes the $I_F R_S$ voltage drop of the series resistance. The non-ideality factor, η, is the only other parameter not accounted for and depends on the diode that is used for measurement. Since ΔV_{BE} is proportional to both η and T, the variations in η cannot be distinguished from variations in temperature. Since the non-ideality factor is not controlled by the temperature sensor, it will directly add to the inaccuracy of the sensor. For the for Intel processor on 65nm process, Intel specifies a +4.06%/−0.897% variation in η from part to part when the processor diode is measured by a circuit that assumes diode equation, [Equation](#page-38-2) 8, as true. As an example, assume a temperature sensor has an accuracy specification of ±1.0°C at a temperature of 80°C (353 Kelvin) and the processor diode has a non-ideality variation of +4.06%/−0.89%. The resulting system accuracy of the processor temperature being sensed will be:

$$
T_{\text{ACC}} = +1.0^{\circ}\text{C} + (+4.06\% \text{ of } 353 \text{ K}) = +15.3^{\circ}\text{C}
$$
 (10)

and

$$
T_{\text{ACC}} = -1.0^{\circ}\text{C} + (-0.89\% \text{ of } 353 \text{ K}) = -4.1^{\circ}\text{C}
$$
 (11)

TruTherm technology uses the transistor equation, [Equation](#page-38-2) 8, resulting in a non-ideality spread that truly reflects the process variation which is very small. The transistor equation non-ideality spread is $\pm 0.39\%$ for the 65nm thermal diode. The resulting accuracy when using TruTherm technology improves to:

$$
T_{\text{ACC}} = \pm 0.75^{\circ}\text{C} + (\pm 0.39\% \text{ of } 353 \text{ K}) = \pm 2.16^{\circ}\text{C}
$$
 (12)

Intel does not specify the diode model ideality and series resistance of the thermal diodes on 45nm so a similar comparison cannot be calculated, but lab experiments have shown similar improvement. For the 45nm processor the ideality spread as specified by Intel is -0.399% to +0.699%. The resulting spread in accuracy when using TruTherm technology with the thermal diode on Intel processors with 45nm process is:

$$
T_{\text{ACC}} = -0.75^{\circ}\text{C} + (-0.39\% \text{ of } 353 \text{ K}) = -2.16^{\circ}\text{C}
$$
 (13)

to

 $T_{\text{ACC}} = +0.75^{\circ}\text{C} + (+0.799\% \text{ of } 353 \text{ K}) = +4.32^{\circ}\text{C}$ (14)

The next error term to be discussed is that due to the series resistance of the thermal diode and printed circuit board traces. The thermal diode series resistance is specified on most processor data sheets. For Intel processors in 45 nm process, this is specified at 4.5Ω typical with a minimum of 3Ω and a maximum of 7Ω. The LM96163 accommodates the typical series resistance of Intel Processor on 45 nm process. The error that is not accounted for is the spread of the processor's series resistance. The equation used to calculate the temperature error due to series resistance (T_{ER}) for the LM96163 is simply:

$$
T_{ER} = \left(0.62 \frac{{}^{0}C}{\Omega}\right) \times R_{PCB}
$$
\n
$$
\tag{15}
$$

Solving [Equation](#page-39-0) 15 for R_{PCB} equal to -1.5Ω to 2.5Ω results in the additional error due to the spread in this series resistance of -0.93°C to +1.55°C. The spread in error cannot be canceled out, as it would require measuring each individual thermal diode device. This is quite difficult and impractical in a large volume production environment.

[Equation](#page-39-0) 15 can also be used to calculate the additional error caused by series resistance on the printed circuit board. Since the variation of the PCB series resistance is minimal, the bulk of the error term is always positive and can simply be cancelled out by subtracting it from the output readings of the LM96163 using the Remote Temperature Offset register.

PCB LAYOUT FOR MINIMIZING NOISE

Figure 16. Ideal Diode Trace Layout

In a noisy environment, such as a processor mother board, layout considerations are very critical. Noise induced on traces running between the remote temperature diode sensor and the LM96163 can cause temperature conversion errors. Keep in mind that the signal level the LM96163 is trying to measure is in microvolts. The following guidelines should be followed:

- 1. Use a low-noise +3.3VDC power supply, and bypass to GND with a 0.1 µF ceramic capacitor in parallel with a 100 pF ceramic capacitor. The 100 pF capacitor should be placed as close as possible to the power supply pin. A bulk capacitance of 10 μ F needs to be in the vicinity of the LM96163's V_{DD} pin.
- 2. A 100 pF diode bypass capacitor is recommended to filter high frequency noise but may not be necessary. Place the recommended 100 pF diode capacitor as close as possible to the LM96163's D+ and D− pins. Make sure the traces to the 100 pF capacitor are matched. The LM96163 can handle capacitance up to 3 nF placed between the D+ and D- pins, see Typical Performance [Characteristics](#page-8-0) curves titled Remote Temperature Reading Sensitivity to Thermal Diode Filter Capacitance.
- 3. Ideally, the LM96163 should be placed within 10 cm of the Processor diode pins with the traces being as straight, short and identical as possible. Trace resistance of 1 Ω can cause as much as 0.62°C of error. This error can be compensated by using the Remote Temperature Offset Registers, since the value placed in these registers will automatically be subtracted from or added to the remote temperature reading.
- 4. Diode traces should be surrounded by a GND guard ring to either side, above and below if possible. This GND guard should not be between the D+ and D− lines. In the event that noise does couple to the diode lines it would be ideal if it is coupled common mode. That is equally to the D+ and D− lines.
- 5. Avoid routing diode traces in close proximity to power supply switching or filtering inductors.
- 6. Avoid running diode traces close to or parallel to high speed digital and bus lines. Diode traces should be kept at least 2 cm apart from the high speed digital traces.
- 7. If it is necessary to cross high speed digital traces, the diode traces and the high speed digital traces should cross at a 90 degree angle.
- 8. The ideal place to connect the LM96163's GND pin is as close as possible to the Processor's GND associated with the sense diode.
- 9. Leakage current between D+ and GND should be kept to a minimum. Thirteen nano-amperes of leakage can cause as much as 0.2°C of error in the diode temperature reading. Keeping the printed circuit board as clean as possible will minimize leakage current.

Noise coupling into the digital lines greater than 400 mVp-p (typical hysteresis) and undershoot less than 500 mV below GND, may prevent successful SMBus communication with the LM96163. SMBus no acknowledge is the most common symptom, causing unnecessary traffic on the bus. Although the SMBus maximum frequency of communication is rather low (100 kHz max), care still needs to be taken to ensure proper termination within a system with multiple parts on the bus and long printed circuit board traces. An RC lowpass filter with a 3 dB corner frequency of about 40 MHz is included on the LM96163's SMBCLK input. Additional resistance can be added in series with the SMBDAT and SMBCLK lines to further help filter noise and ringing. Minimize noise coupling by keeping digital traces out of switching power supply areas as well as ensuring that digital lines containing high speed data communications cross at right angles to the SMBDAT and SMBCLK lines.

REVISION HISTORY

PACKAGING INFORMATION

(1) The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBSOLETE: TI has discontinued the production of the device.

⁽²⁾ RoHS: TI defines "RoHS" to mean semiconductor products that are compliant with the current EU RoHS requirements for all 10 RoHS substances, including the requirement that RoHS substance do not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, "RoHS" products are suitable for use in specified lead-free processes. TI may reference these types of products as "Pb-Free".

RoHS Exempt: TI defines "RoHS Exempt" to mean products that contain lead but are compliant with EU RoHS pursuant to a specific EU RoHS exemption.

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(3) MSL, Peak Temp. - The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

(4) There may be additional marking, which relates to the logo, the lot trace code information, or the environmental category on the device.

(5) Multiple Device Markings will be inside parentheses. Only one Device Marking contained in parentheses and separated by a "~" will appear on a device. If a line is indented then it is a continuation of the previous line and the two combined represent the entire Device Marking for that device.

(6) Lead finish/Ball material - Orderable Devices may have multiple material finish options. Finish options are separated by a vertical ruled line. Lead finish/Ball material values may wrap to two lines if the finish value exceeds the maximum column width.

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TAPE AND REEL INFORMATION

QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE

PACKAGE MATERIALS INFORMATION

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*All dimensions are nominal

Pack Materials-Page 2

PACKAGE OUTLINE

DSC0010B WSON - 0.8 mm max height

PLASTIC SMALL OUTLINE - NO LEAD

NOTES:

- 1. All linear dimensions are in millimeters. Any dimensions in parenthesis are for reference only. Dimensioning and tolerancing per ASME Y14.5M.
- 2. This drawing is subject to change without notice.

3. The package thermal pad must be soldered to the printed circuit board for thermal and mechanical performance.

EXAMPLE BOARD LAYOUT

DSC0010B WSON - 0.8 mm max height

PLASTIC SMALL OUTLINE - NO LEAD

NOTES: (continued)

4. This package is designed to be soldered to a thermal pad on the board. For more information, see Texas Instruments literature number SLUA271 (www.ti.com/lit/slua271).

EXAMPLE STENCIL DESIGN

DSC0010B WSON - 0.8 mm max height

PLASTIC SMALL OUTLINE - NO LEAD

NOTES: (continued)

5. Laser cutting apertures with trapezoidal walls and rounded corners may offer better paste release. IPC-7525 may have alternate design recommendations.

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